

# B5819LW

Rev.B Jul.-2024

## 描述 / Descriptions

SOD-123 塑封封装 肖特基二极管。  
Schottky Diode in a SOD-123 Plastic Package.

## 特征 / Features

低正向压降，无卤产品。  
Low positive pressure drop, HF Product.

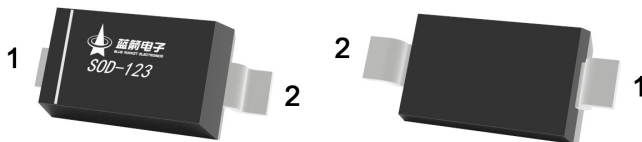
## 用途 / Applications

一般用途。  
General purpose.

## 内部等效电路 / Equivalent Circuit



## 引脚排列 / Pinning



PIN1:Cathode

PIN2:Anode

## 印章代码 / Marking

Model	B5819LW
Marking	SL

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

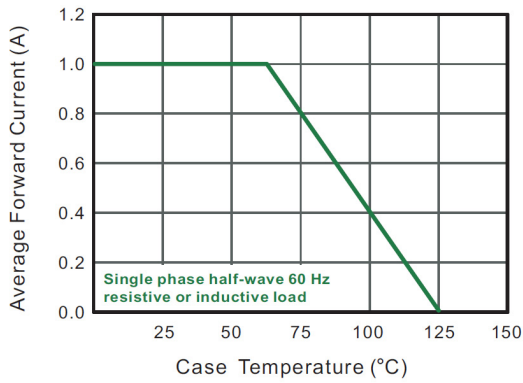
参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	40	V
Maximum RMS voltage	$V_{R(RMS)}$	28	V
Maximum DC Blocking Voltage	$V_{DC}$	40	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1	A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed On Rated Load (JEDEC method)	$I_{FSM}$	25	A
Typical Junction Capacitance	$C_j$	110	pF
Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 125	°C

**电性能参数 / Electrical Characteristics(Ta=25°C)**

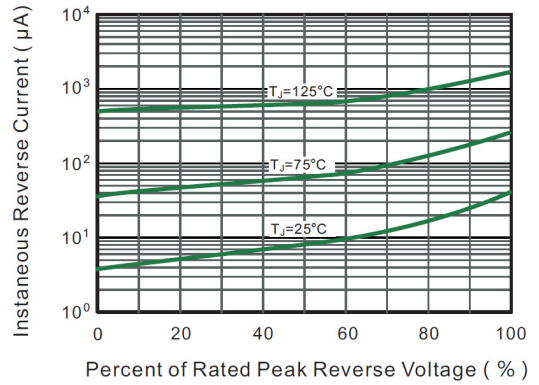
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating			单位 Unit
			最小值 Min	典型值 Typ	最大值 Max	
Forward Voltage	$V_F$	$I_F=100mA$			0.315	V
		$I_F=1A$			0.48	
		$I_F=2A$			0.50	
Maximum Instantaneous Reverse Current at Rated DC Reverse Voltage	$I_R$	$T_A = 25^\circ C$			1	mA
		$T_A = 100^\circ C$			10	

**电参数曲线图 / Electrical Characteristic Curve**

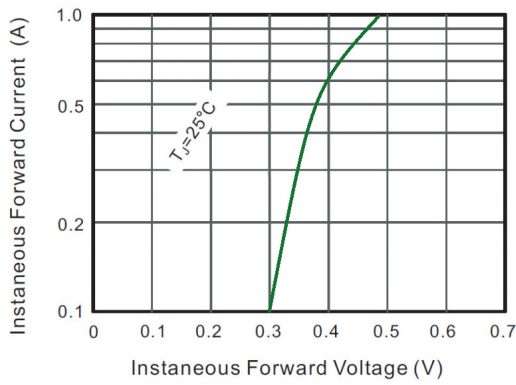
**Fig.1 Forward Current Derating Curve**



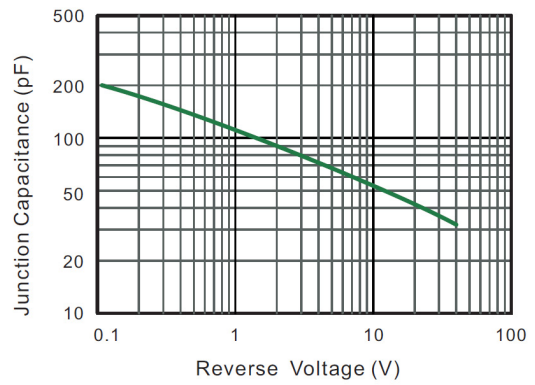
**Fig.2 Typical Reverse Characteristics**



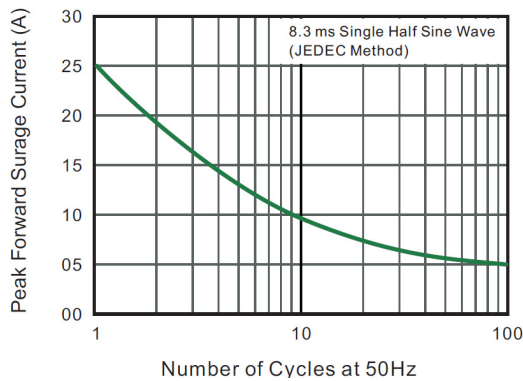
**Fig.3 Typical Forward Characteristic**



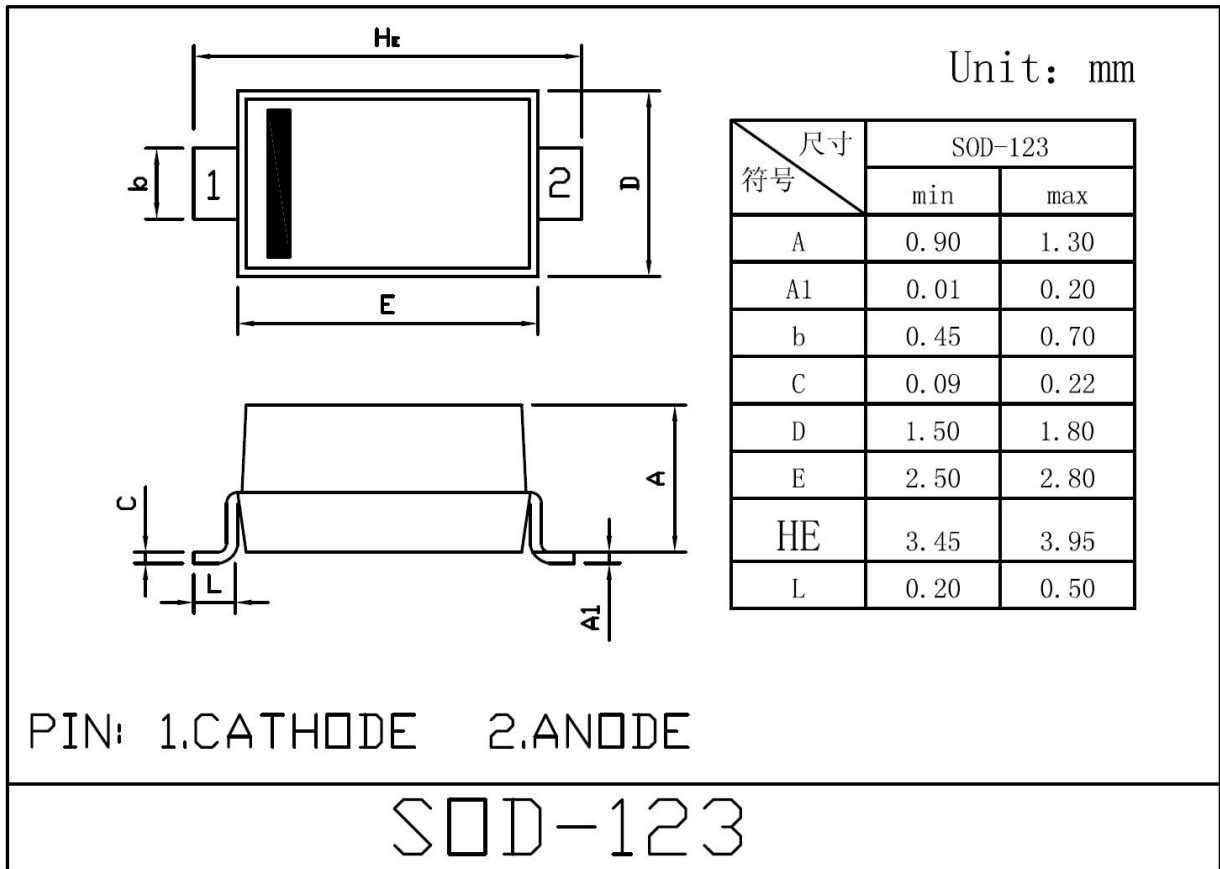
**Fig.4 Typical Junction Capacitance**



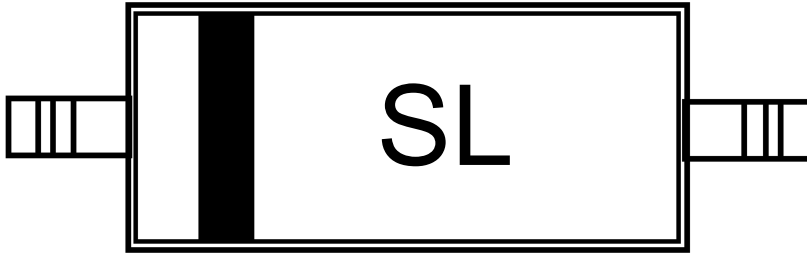
**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**



外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions



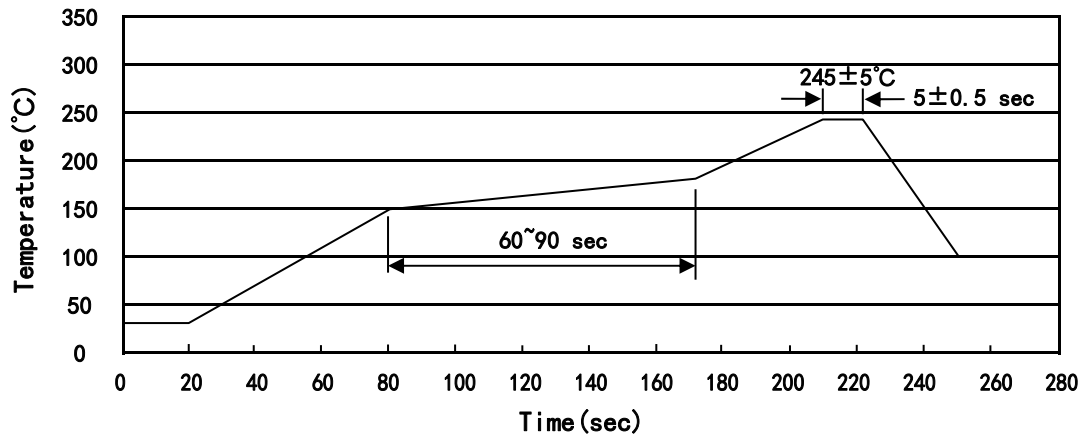
说明：

SL： 为型号代码

Note:

SL: Product Type Code

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C      时间：10±1 sec.      Temp.:260±5°C      Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-123	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

**使用说明 / Notices**